

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Inventor: Wei Pan, Yoshi Ono, David

R. Evans, and Sheng Teng Hsu

Serial No.: 09/819,296

Filed: March 27, 2001

Title: MULTI-LAYERED BARRIER

> METAL THIN FILMS FOR Cu INTERCONNECT BY

ALCVD

February 25, 2002

ATTORNEY DOCKET

No. SLA0515

Group Art Unit: 2811

Examiner:

Hung K. Vu

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited in the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Hon. Commissioner for Patents, Washington D.C. 2023, on February 25, 2002.

David C. Ripma, Reg. No. 27,672

Signature Date: February 25, 2002

RESPONSE TO RESTRICTION REQUIREMENT

Hon. Commissioner for Patents Washington, D.C. 20231

Sir:

This communication responds to an Office Action dated February 15, 2002 in the above-identified patent application. In the Office Action the Examiner requires restriction to one of the following inventions:

Group I. Claims 1-7, drawn to a device; and

Group II. Claims 8-20, drawn to a method.

Applicants hereby elect to pursue the Group II claims, claims 8-20, drawn to a method.

By:

C. Ripma,

Respectfully submitted

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